

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"20050241761".pn.	US-PGPUB	OR	ON	2009/01/28 13:43
L2	5	("5655357" "5837094" "6012334" "6238488" "6579371").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 13:43
L3	0	1 and means	US-PGPUB	OR	ON	2009/01/28 13:43
L4	1	1 and detect\$4 same chang \$3	US-PGPUB	OR	ON	2009/01/28 13:46
L5	1	"5152172".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 13:59
L6	1	5 and (vibrat\$4 resona\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 13:59
L7	1	5 and (rotor\$1 rotat\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 14:13
L8	1	1 and stabili\$4	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 14:32
L9	0	1 and instabilit\$2	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 14:33
L10	1	1 and (stabil\$5 unstabl\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 14:34
S1	176	("KANNAN, HIROSHI" "ISHIZAKA, TADAHIRO" "KOJIMA, YASUHIKO" "OSHIMA, YASUHIRO" "SHIGEOKA, TAKASHI").in.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 16:34
S2	3	S1 and (semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces) and ((endpoint endpoints (end adj (point points))))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 16:38
S3	102	S1 and (semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 16:39
S4	1	"20050241761".pn.	US-PGPUB	OR	ON	2008/05/31 16:40
S5	1	S4 and (end with point\$1)	US-PGPUB	OR	ON	2008/05/31 16:41
S6	87	S3 and ((end with point\$1) finish\$3 conclusion conclud \$3 terminat\$3 complet\$3)	US-PGPUB; USPAT	OR	ON	2008/05/31 16:46
S7	26	S6 and ((no without) with plasma)	US-PGPUB; USPAT	OR	ON	2008/05/31 16:46

S8	263	"TOKYO ELECTRON".as. and (semiconductor substrates wafer wafers workpiece workpieces) and ((endpoint endpoints (end adj (point points))))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 16:49
S9	128	S8 and ((no without) with plasma)	US-PGPUB; USPAT	OR	ON	2008/05/31 16:50
S10	20	S9 and ((endpoint endpoints (end adj (point points))) with (clean\$3 flush\$3 purg \$3))	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 16:54
S11	1	"6737666".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 17:10
S12	2	("5902403" "6079426"). PN. OR ("6660101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/31 17:17
S13	16924	tachibana.in.	FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 17:19
S14	18	S13 and (end adj point)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 17:20
S15	2	("5837094" "6238488").pn.	USPAT	OR	ON	2008/05/31 17:33
S16	99514	(semiconductor substrates wafer wafers workpiece workpieces) and (treat\$4 clean\$4 process\$3) and (endpoint\$s (end with point\$1))	US-PGPUB; USPAT	OR	ON	2008/05/31 17:51
S17	13898	S16 and ("118" "134" "156" "216" "250" "427" "438"). clas.	US-PGPUB; USPAT	OR	ON	2008/05/31 17:56
S18	1169	S17 and (118/715 134/18,21,22,1,902 156/345.1,345.24 216/59 427/248.1 438/5,14,17,905). ccls.	US-PGPUB; USPAT	OR	ON	2008/05/31 18:11
S19	261	S18 and (operat\$3 with detect\$3)	US-PGPUB; USPAT	OR	ON	2008/05/31 18:12
S20	127	S19 and (operat\$3 near3 detect\$3)	US-PGPUB; USPAT	OR	ON	2008/05/31 18:12
S21	40	S20 and exhaust\$3	US-PGPUB; USPAT	OR	ON	2008/05/31 18:13
S22	2805	(semiconductor substrates wafer wafers workpiece workpieces) and (treat\$4 clean\$4 process\$3) and (endpoint\$s (end with point\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 18:14

S23	85	S22 and (operat\$3 with detect\$3)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 18:14
S24	3	S23 and exhaust\$3	FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 18:14
S25	3	S23 and (exhaust\$3 vent\$3)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 18:17
S26	145	(S11 S14 S15 S21 S23)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 18:17
S27	5	S26 and vibrat\$3 and rotat \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/05/31 18:18
S28	1	"20050241761".pn. and (process\$3 near\$3 gas\$2)	US-PGPUB	OR	ON	2008/05/31 19:09
S29	1	"20050241761".pn. and (clean\$4 near\$3 gas\$2)	US-PGPUB	OR	ON	2008/05/31 19:10
S30	1	"20050241761".pn. and (operat\$3 near\$3 state near\$3 detect\$3)	US-PGPUB	OR	ON	2008/05/31 19:17
S31	1	"20050241761".pn. and process\$3	US-PGPUB	OR	ON	2008/05/31 19:32
S32	1	"6737666".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/02 09:48
S33	16930	tachibana.in.	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 09:48
S34	18	S33 and (end adj point)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 09:48
S35	2	("5837094" "6238488").pn.	USPAT	OR	ON	2008/06/02 09:48
S36	99514	(semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces) and (treat\$4 clean\$4 process\$3) and (endpoint\$ end with point\$1))	US-PGPUB; USPAT	OR	ON	2008/06/02 09:48
S37	13898	S36 and ("118" "134" "156" "216" "250" "427" "438"). clas.	US-PGPUB; USPAT	OR	ON	2008/06/02 09:48
S38	1169	S37 and (118/715 134/18,21,22,1,902 156/345,1,345,24 216/59 427/248,1 438/5,14,17,905). ocls.	US-PGPUB; USPAT	OR	ON	2008/06/02 09:48
S39	261	S38 and (operat\$3 with detect\$3)	US-PGPUB; USPAT	OR	ON	2008/06/02 09:48
S40	127	S39 and (operat\$3 near\$3 detect\$3)	US-PGPUB; USPAT	OR	ON	2008/06/02 09:48

S41	40	S40 and exhaust\$3	US-PGPUB; USPAT	OR	ON	2008/06/02 09:48
S42	2806	(semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces) and (treat\$4 clean\$4 process\$3) and (endpoint\$ (end with point\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 09:48
S43	85	S42 and (operat\$3 with detect\$3)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 09:48
S44	145	(S32 S34 S35 S41 S43)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 09:48
S45	6	S44 and vibrat\$5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 09:54
S46	12	(S36 S42) and (vibrat\$5 with (detect\$3 sens\$3 analyz \$3) with (exhaust\$3 vent \$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:06
S47	311	vibration with detect\$4 with exhaust\$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:13
S48	6	S47 and (semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:14
S49	84	S47 and (vibration near5 detect\$4 near5 exhaust\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:16
S50	44	S49 and (vibration near3 detect\$4 near3 exhaust\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:16
S51	747	vibrat\$5 with (detect\$4 sens \$3 analy\$4 instrument\$5) with (exhaust\$3 vent\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:21
S52	195	S51 and (vibrat\$5 near5 (detect\$4 sens\$3 analy\$4 instrument\$5) near5 (exhaust\$3 vent\$3))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:21
S53	80	S52 and (vibrat\$5 near3 (detect\$4 sens\$3 analy\$4 instrument\$5) near3 (exhaust\$3 vent\$3))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:22

S54	2	S53 and (vibrat\$5 adj (detect\$4 sens\$3 analy\$4 instrument\$5) adj (exhaust\$3 vent\$3))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:22
S55	1	S53 and (vibrat\$5 near3 (sound with wave\$1))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:23
S56	2	S53 and (vibrat\$5 with (sound with wave\$1))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 10:24
S57	1	"5837094".pn.	USPAT	OR	ON	2008/06/02 10:43
S58	0	S57 and vibrat\$5	USPAT	OR	ON	2008/06/02 10:43
S59	77	S51 and (vibrat\$5 with sound\$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:07
S60	16	S59 and (vibrat\$5 with (sound\$1 with wav\$3))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:07
S61	77	S59 and (vibrat\$5 with sound\$1)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:15
S62	51	S59 and (vibrat\$5 with (sound\$1 with (detect\$4 sens\$3 analy\$4 instrument\$5)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:16
S63	77	S51 and (vibrat\$5 with ((sound\$1 acoustic\$1) with (detect\$4 sens\$3 analy\$4 instrument\$5)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:24
S64	22	S63 and (vibrat\$5 with ((sound\$1 acoustic\$1) with wav\$3))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:25
S65	6	("2000353684" "2000353685" "11121430"). pn.	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:28
S66	1	S65 and (exhaust\$3 vent\$3)	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:31
S67	107	(S51 S65) and (vibrat\$5 with (intens\$3 amplitud\$2))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:40

S68	75	S67 and (vibrat\$5 with (intens\$3 amplitud\$2) with (detect\$4 sens\$3 analy\$4 instrument\$5))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:40
S69	1	S68 and (vibrat\$5 with (intens\$3 amplitud\$2) with (detect\$4 sens\$3 analy\$4 instrument\$5) with (endpoint endpoints (end adj (point points))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:42
S70	12	("4721874" "4741200" "4961345" "5334303" "5374521" "5485744" "5545461" "5600197" "5698931" "5889351").PN. OR ("6047590").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/02 11:50
S71	0	S70 and (vibrat\$5 with (intens\$3 amplitud\$2) with (detect\$4 sens\$3 analy\$4 instrument\$5))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:50
S72	17	S68 and (semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 11:55
S73	2	"11121430".pn.	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:15
S74	1	"5837094".pn.	USPAT	OR	ON	2008/06/02 12:16
S75	3	(S73 S74)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:16
S76	2	S75 and (sound\$2 acoustic \$2)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:17
S77	1	"62210270".pn.	FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:18
S78	3	(S73 S77)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:19
S80	2	S78 and (sound\$2 acoustic \$2)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:19
S81	2	(S74 S77)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:20
S82	0	S81 and (sound\$2 acoustic \$2)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:20
S83	2	"6012334".pn.	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:35

S84	0	S83 and exhaust\$3	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:38
S85	0	S83 and vent\$3	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:38
S86	2	S83 and sound	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:47
S87	2	S83 and (sound with wave \$1)	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:48
S89	2	S83 and "1"	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 12:52
S90	9	("5837094" "62210270" "6012334" "11121430" "5655357").pn.	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:09
S91	2	S90 and rotat\$5	USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:09
S92	8421	(semiconductor semiconductors substrate substrates wafer wafers workpiece workpieces) with (exhaust\$3 vent\$3 vacuum \$3) with rotat\$5	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:11
S93	388	S92 and (exhaust\$3 vent\$3 vacuum\$3) with rotat\$5 with (detect\$4 sens\$3 analy \$4 instrument\$5)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:12
S94	80	S93 and (exhaust\$3 vent\$3 vacuum\$3) near5 rotat\$5 near5 (detect\$4 sens\$3 analy\$4 instrument\$5)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:12
S95	46	S94 and (exhaust\$3 vent\$3 vacuum\$3) near3 rotat\$5 near3 (detect\$4 sens\$3 analy\$4 instrument\$5)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:13
S96	6	S94 and exhaust\$3 near3 rotat\$5 near3 (detect\$4 sens \$3 analy\$4 instrument\$5)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:14
S97	0	("2002/0174829").URPN.	USPAT	OR	ON	2008/06/02 14:23
S98	7	S93 and (vane\$1 anemometer\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/06/02 14:31
S99	1	"20050241761".pn.	US-PGPUB	OR	ON	2009/01/27 15:28

S100	5	("5655357" "5837094" "6012334" "6238488" "6579371"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/27 15:55
S101	1	"20050241761". pn.	US-PGPUB	OR	ON	2009/01/28 11:27
S102	5	("5655357" "5837094" "6012334" "6238488" "6579371"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 11:27
S103	1	S102 and blade\$1	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 11:28
S104	1	S101 and blade\$1	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 11:32
S105	4	S102 and (pump\$3 rotor\$1 blade\$1)	US-PGPUB; USPAT; USOCR	OR	ON	2009/01/28 11:33
S106	563	rotor\$1 same blade\$1 same (gas gasses exhaust\$4 efflu\$4 stream\$1 fluid\$1) same (detect\$4 monitor\$3 measur\$5 analy\$4) same (weight mass volume volumetric flow rate\$1 flowrate\$1)	US-PGPUB; USPAT	OR	ON	2009/01/28 11:55
S107	56	S106 and (detect\$4 monitor\$3 measur\$5 analy\$4) same (weight mass volume volumetric flow rate\$1 flowrate\$1) same (gas gasses exhaust\$4 efflu\$4 stream\$1 fluid\$1) same (collid\$3 collision\$1 bump\$3 crash\$3 hit\$4 strik\$3 imping\$3)	US-PGPUB; USPAT	OR	ON	2009/01/28 11:58
S108	42	S107 and (detect\$4 monitor\$3 measur\$5 analy\$4) same (weight mass volume volumetric flow rate\$1 flowrate\$1) same (gas gasses exhaust\$4 efflu\$4 stream\$1 fluid\$1) same (collid\$3 collision\$1 bump\$3 crash\$3 hit\$4 strik\$3 imping\$3) same blade\$1	US-PGPUB; USPAT	OR	ON	2009/01/28 11:58
S109	3	S108 and (sound\$1 acoustic\$1 sonic ultrasonic ultrasound) same wave\$1	US-PGPUB; USPAT	OR	ON	2009/01/28 12:05
S110	0	("2005/0241761"). UPRN.	USPAT	OR	ON	2009/01/28 12:05
S111	30	S106 and (sound\$1 acoustic\$1 sonic ultrasonic ultrasound) same wave\$1	US-PGPUB; USPAT	OR	ON	2009/01/28 12:06

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